

What is Claimed is:

1. A ceramic package for internally mounting at least one component, comprising:

5 a layered structure formed by stacking a plurality of ceramic sheets one atop another, having an internal cavity for housing the component and internal patterns in at least a portion of the ceramic sheets;

10 a lid mounted on the layered structure above the cavity to maintain the cavity airtight;

outside connection terminals formed on outer portions of the layered structure;

15 internal connection patterns separately formed horizontally in at least two of the ceramic sheets to be electrically connected with the outside connection terminals; and

inside connection terminals formed within the cavity to be electrically connected with the component and at least a portion of the internal connection patterns.

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2. The ceramic package as set forth in claim 1, wherein the separate internal connection patterns are electrically connected through via holes.

25 3. The ceramic package as set forth in claim 1, wherein

the internal connection patterns are separately formed in adjacent ones of the ceramic sheets.

4. The ceramic package as set forth in claim 1, wherein
5 the internal connection patterns comprise upper internal connection patterns formed adjacent to the lid and lower internal connection patterns connected with the inside connection terminals.

10 5. The ceramic package as set forth in claim 4, wherein the lower internal connection patterns comprise a first pattern which is formed on a ceramic sheet as that of the inside connection terminals for electric connection therewith, and a second pattern which is connected with the outside connection
15 terminals and formed in a second ceramic sheet different from that of the first pattern.

6. The ceramic package as set forth in claim 4, wherein the upper internal connection patterns comprise a first pattern
20 formed on a layer on which the lid is mounted, and a second pattern which is connected with the outside connection terminals and formed on a ceramic sheets different from that of the first pattern.

25 7. The ceramic package as set forth in claim 4, further

comprising inside patterns for realizing circuit elements in at least one of the ceramic sheets which underlies the lower internal connection patterns.

5 8. A fabrication method of a ceramic package capable of mounting components within a cavity, the method comprising the steps of:

 preparing a plurality of ceramic sheets;

 forming pattern layers in at least a portion of the ceramic 10 sheets to realize circuit elements;

 forming outside connection terminals for signal interchange with the outside and forming inside connection terminals connected with the components in a portion of the ceramic sheets;

15 separately forming internal connection patterns on at least two of the ceramic sheets, for connecting the outside connection terminals with the lid mounted over the cavity or with the inside connection terminals;

 forming conductive via holes in a portion of the ceramic 20 sheets to electrically connect the separate internal connection patterns which are formed in the ceramic sheets; and

 stacking the ceramic sheets one atop another.

9. The fabrication method as set forth in claim 8, wherein 25 the internal connection patterns are separately formed in

adjacent ones of the ceramic sheets.

10. The fabrication method as set forth in claim 8,
wherein the internal connection patterns comprise upper
5 internal connection patterns formed adjacent to the lid and
second internal connection patterns connected with the inside
connection terminals.

11. The fabrication method as set forth in claim 10,
10 wherein the lower internal connection patterns comprise a first
pattern which is formed on a same ceramic sheet as that of the
inside connection terminals for electric connection therewith,
and a second pattern which is connected with the outside
connection terminals and formed in a second ceramic sheet
15 different from that of the first pattern.

12. The fabrication method as set forth in claim 10,
wherein the upper internal connection patterns comprise a first
pattern formed on a layer on which the lid is mounted, and a
20 second pattern which is connected with the outside connection
terminals and formed on a ceramic sheet different from that of
the first pattern.

13. The fabrication method as set forth in claim 10,
25 wherein inside patterns for realizing circuit elements are

provided in at least one of the ceramic sheets which underlies the lower internal connection patterns.